

### **Effect of Defect Dynamics on Reliability of X7R Multilayer Ceramic Capacitors**

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#### **Multilayer Ceramic Capacitors (MLCCs)**



[1] Samsung Electro-Mechanics[2] https://www.yuden.co.jp/ap/solutions/mlcc/

**(** 

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Feature phone

Smartphone

PC

LED TV

Electric vehicle

## **MLCCs Reliability**



# Faulty \$5 Parts Cause 18-Month, \$1 Billion Delay to Navy, Air Force Nuclear Upgrades

#### By: Ben Werner

#### September 25, 2019 4:46 PM

Replacement capacitors are being produced but will cost about \$75 per unit, compared with the \$5 per unit cost of the off-the-shelf capacitors that failed stress testing.

"The use of commercial-off-the-shelf electric components needs to be improved to reduce future COTS-related risk," Verdon said.



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[1] SAMSUNG ELECTRO-MECHANICS

[2] https://news.usni.org/2019/09/25/faulty-5-parts-cause-18-month-1-billion-delay-to-navy-air-force-nuclear-upgrades

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## **MLCCs' Reliability**

Electrode discontinuities: Lower volumetric capacitance and electric field enhancement



<u>Rough interfaces</u>: Lead to electric field enhancement and thus, higher leakage current

[1] Polotai, Anton V., et al. Journal of the American Ceramic Society 90.12 (2007): 3811-3817.
 [2] Samantaray, Malay M., et al. Journal of the American Ceramic Society 95.1 (2012): 264-268.



250°C/min to 1300C

3000°C/min to 1300C

4



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### **Quality Control & Lifetime Predictions**



Hnatek, Eugene R. Practical reliability of electronic equipment and products. CRC press, 2002.
 W.-E. Liu, The Pennsylvania State University, 2009.

[2] W.-E. Liu, The Pennsylvania State Univer



### **Burn-in Test**

MIL-PRF-32535A:

• "Voltage conditioning shall consist of applying twice the rated voltage to the units at the maximum rated temperature of +125°C +4°C, -0°C for a minimum of 168 hours and a maximum of 264 hours."



[1] Department of defense (2017) MIL-PRF-32535A.

[2] https://www.kemet.com/en/us/technical-resources/new-options-when-failure-is-not-an-option.html

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#### **Hazard Rate Curve**

![](_page_6_Figure_1.jpeg)

#### **Aggressive Burn-in May Cause an Irreversible Damage to Grain Boundary Barriers**

![](_page_6_Picture_3.jpeg)

# **Thermally Stimulated Depolarization Current (TSDC)**

![](_page_7_Figure_1.jpeg)

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#### **TSDC** as a Screening Tool for MLCCs

- > TSDC is being used as a screening method to detect infant failures
- Some companies now use it as an acceptance screen for lots where high reliability is required
  Acceptable TSC Performance

![](_page_8_Figure_3.jpeg)

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#### Thermally Stimulated Depolarization Current (TSDC)

![](_page_9_Figure_1.jpeg)

[1] Yousefian P., and C. A. Randall, Journal of Materials Science 57.33 (2022): 15913-15918.

![](_page_9_Picture_3.jpeg)

### **Highly Accelerated Life Test (HALT)**

![](_page_10_Picture_1.jpeg)

![](_page_10_Picture_2.jpeg)

**Before HALT** 

![](_page_10_Figure_4.jpeg)

![](_page_10_Figure_5.jpeg)

![](_page_10_Figure_6.jpeg)

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#### **Highly Accelerated Life Test (HALT)**

![](_page_11_Figure_1.jpeg)

2-parameter Weibull Distribution

PDF: 
$$f(t) = \frac{\beta t^{\beta - 1}}{\alpha^{\beta}} e^{-\left(\frac{t}{\alpha}\right)^{\beta}}$$

 $\alpha$ : Scale parameter

 $\beta$ : Shape parameter

Weibull Mixture Model  $PDF_{mixture} = p \times PDF_1 + (1 - p) \times PDF_2$ 

![](_page_11_Picture_7.jpeg)

## **Effect of Burn-in Test**

![](_page_12_Figure_1.jpeg)

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A)

#### **Hazard Rate Curve**

![](_page_13_Figure_1.jpeg)

#### **Aggressive Burn-in Cause an Irreversible Damage to Grain Boundary Barriers**

[1] Yousefian P., and C. A. Randall, *Journal of Materials Science* 57.33 (2022): 15913-15918.

![](_page_13_Picture_4.jpeg)

#### **Lifetime Prediction Models**

# Empirical Models Eyring Model

$$\frac{t_1}{t_2} = \left(\frac{V_2}{V_1}\right)^n \exp\left(\frac{E_A}{k_B}\left(\frac{1}{T_1} - \frac{1}{T_2}\right)\right)$$

# n should be a constant and independent of V and T

#### **Tipping Point Model**

![](_page_14_Figure_5.jpeg)

$$t_{crit} = \frac{\rho_{crit}}{a\vartheta Nq} \left[ exp\left(-\frac{E_a}{k_B T}\right) sinh\left(\frac{qaE_{app}}{2k_B T}\right) \right]^{-1}$$
$$\ln(t) = C(T) - \ln\left(sinh\left(\frac{\beta'E_{app}}{T}\right)\right)$$

[1] Randall, C. A., et al., *Journal of Applied Physics* 113.1 (2013): 014101.
[2] Morita, Koichiro, et al., *Japanese Journal of Applied Physics* 57.11S (2018): 11UC03.

#### **Lifetime Prediction Models**

![](_page_15_Figure_1.jpeg)

![](_page_15_Figure_2.jpeg)

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[1] Yousefian P., et al.

Applied Physics Letters

122.11 (2023): 112902.

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#### What is Next?

![](_page_16_Figure_1.jpeg)

#### Machine Learning-Based Lifetime Prediction Model

![](_page_16_Figure_3.jpeg)

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### Summary

- ✓ We demonstrated that TSDC is a powerful technique for MLCCs' screening
- ✓ Intragranular and transgranular electromigration of oxygen vacancies after burn-in test was observed. and reduction of lifetime in screened MLCCs.
- ✓ Determined the effect of Burn in conditions on the distribution of MLCC's failure time.
- ✓ We quantified a freak population of failures in MLCCs after short burn-in process.
- ✓ Limitation of Eyring model on predicting lifetime of MLCCs was demonstrated.
- ✓ The tipping point model appears to be more systematic and predictable across all testing conditions
- ✓ We are investigating AI methods for predicting not only MTTF but also failure times data distribution.

![](_page_17_Picture_8.jpeg)

#### Acknowledgments

- This work is supported by the National Science Foundation, as part of the Center for Dielectrics and Piezoelectrics under Grant Nos. IIP-1841453 and IIP-1841466".
- Materials Characterization Lab staff
- Jeff Long, Steve Perini, and Mike Norrell

![](_page_18_Picture_4.jpeg)

![](_page_18_Picture_5.jpeg)

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center for dielectrics and piezoelectrics

![](_page_18_Picture_7.jpeg)

![](_page_18_Picture_8.jpeg)

![](_page_19_Picture_0.jpeg)